



TARGET THICKNESS: 0.078"
NUMBER OF LAYERS: 04

MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

4 Layer StackUp (0.078") L04-078-1oz1oz		Thickness (inches)
Layer 1	1 oz foil plated to approximate* thickness 0.0024"	0.0024
Prepreg	Bonding ply (1x 1080, 2x2116) Average Dielectric Constant 4.5	0.0106
Layer 2	1 oz foil thickness	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.021
Prepreg	Bonding ply (2x2116, 1x1080) Average Dielectric Constant 4.5	0.0106
Core	Laminate Core Average Dielectric Constant 4.5	0.021
Layer 3	1 oz foil thickness	0.0014
Prepreg	Bonding ply (2x2116, 1x1080) Average Dielectric Constant 4.5	0.0106
Layer 4	1 oz foil plated to approximate* thickness 0.0024"	0.0024
"Thickness does not include soldermask or surface finish"		0.0814

NOTES: